Ziptronix licenses DBI® and ZiBond® patented technologies to Tezzaron Semiconductor for advanced 3D memory and 3D integrated assemblies

Ziptronix has signed a licensing agreement with Tezzaron Semiconductor for the use of patents regarding Ziptronix’s direct bonding technologies, DBI® and Direct Bond Interconnect (DBI®).

“DBI, ZiBond, and FaStack make a formidable technologies,” said Bob Patti, CTO of Tezzaron. “3D memory and 3D integrated assemblies and system-level architecture options on these technologies on product roadmaps and companies with technology data that can be evaluated and a cost assessment is provided. Imece INSITE program allows for product roadmaps steering, early feedback toward technology specification, early decisions on required architectural design changes and faster learning cycles for technology adoption with reduced risks.”

Imec and Altera broaden strategic collaboration on 3DIC

Imec and Altera Corporation announced the broadening of their strategic research collaboration in the framework of imec’s INSITE program. Initially focusing on technology insight into 3-D process technologies, collaboration between imec and Altera will now be broadened toward pathfinding and system-level architecture options on power, performance, and area (PPA) are evaluated and a cost assessment is provided. Imece INSITE program allows for product roadmaps steering, early feedback toward technology specification, early decisions on required architectural design changes and faster learning cycles for technology adoption with reduced risks.

www.imec.be - www.altera.com

Imec's INSITE program allows for product roadmaps steering, early feedback toward technology specification, early decisions on required architectural design changes and faster learning cycles for technology adoption with reduced risks.